Name...

Reg. No..

## EIGHTH SEMESTER B.TECH. (ENGINEERING) DEGREE EXAMINATION MAY/JUNE 2007

Time: Three Hours

Maximum: 100 Marks

Answer all questions of I Each question carries 5 marks.

EC 2K 803—MICROELECTRONIC TECHNOLOGY

- I. 1 What is drive in diffusion? How is its analytic solutions found?
  - 2 What is molecular beam epitaxy (MBE)?
  - 3 What is the feature of Silicon on Insulator isolation technique? Explain.
  - 4 What is the difference between junction and oxide isolation? Where each one is used?
  - 5 Compare bipolar technology with CMOS technology.
  - 6 Describe the n tub and p tub implant of a twin tub CMOS structure.
  - 7 How is cell hierarchy helpful in lay out of VLSI circuits?
  - 8 How is lay out of junction isolated BJT done?

 $(8 \times 5 = 40 \text{ marks})$ 

Answer all questions of II to V. Each question carries 15 marks.

II. 1 Draw the schematic view of channeling. How is channeling characterized? Define that parameter which characterize channel.

(15 marks)

Or

2 What is the difference between proximity printing and projection printing? Compare their features.

(15 marks)

III. 1 What is meant by SILO process? Describe.

(15 marks)

Or

When and where implanted ohmic contact is used? How is this done?

(15 marks)

IV. 1 Describe the fabrication process sequence of NMOS IC technology.

(15 marks)

Or

2 Compare the effects of hot carriers in CMOS and bipolar processes.

(15 marks)

V. 1 Describe the lay out rules for metal layers, poly 1 and 2.

(15 marks)

Or

2 Explain CMOS inverter gate lay out with sketches.

(15 marks)

 $(4 \times 15 = 60 \text{ marks})$